

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT7475998

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SEONGMIN PARK	07/25/2022
JIHWA LEE	07/25/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ACTIONPOWER CORP.
<b>Street Address:</b>	1838 NAMBUSUNHWAN-RO, 11F, GWANAK-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	08788
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17880501
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(206)682-6031
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	206-622-4900
<b>Email:</b>	kathleen.lozano@seedip.com
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<b>Address Line 1:</b>	701 FIFTH AVENUE
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<b>ATTORNEY DOCKET NUMBER:</b>	100257.401
<b>NAME OF SUBMITTER:</b>	HYUN KYU LEE
<b>SIGNATURE:</b>	/HYUN KYU LEE L1306/
<b>DATE SIGNED:</b>	08/09/2022
<b>Total Attachments: 4</b>	
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source=401Assignment#page3.tif	
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ASSIGNMENT

WHEREAS, we,

Name	Address	
Seongmin PARK	64dong 205ho, 58, Apgujeong-ro 39-gil, Gangnam-gu, Seoul 06003, Republic of Korea	; and
Jihwa LEE	410ho, 1798, Nambusunhwan-ro, Gwanak-gu, Seoul 08786, Republic of Korea	

(hereinafter referred to as ASSIGNORS), having mailing addresses as listed above, are the joint inventors of an invention entitled "METHOD FOR DIALOGUE SUMMARIZATION WITH WORD GRAPHS," as described and claimed in the specification forming part of an application for United States letters patent executed herewith;

WHEREAS,

Corporation Name	Address
ActionPower Corp.	1838 Nambusunhwan-ro, 11F, Gwanak-gu, Seoul 08788, Republic of Korea

(hereinafter referred to as ASSIGNEE), a corporation of Republic of Korea having a place of business at the address listed above, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEE, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, and including the right to sue and collect damages for past and present infringement of said letters patent; said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by

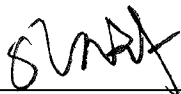
ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

\_\_\_\_\_ 25 July 2022 \_\_\_\_\_  
Date Seongmin Park (Assignor)  
Seongmin PARK

I certify that I know or have satisfactory evidence that Seongmin PARK signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

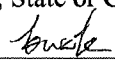
Date \_\_\_\_\_ 25 July 2022 \_\_\_\_\_ Signed at \_\_\_\_\_ Seoul, Republic of Korea  
Seung ho KWAK (Name of Witness) \_\_\_\_\_ Kwak (Signature of Witness)

25 July 2022  
Date

 (Assignor)  
Jihwa LEE

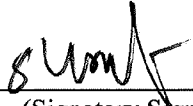
I certify that I know or have satisfactory evidence that Jihwa LEE signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date 25 July 2022  
Seungho KWAK  
(Name of Witness)

Signed at Seoul, Republic of Korea.  
(City, State or Country)  
  
(Signature of Witness)

**ActionPower Corp.**

25 July 2022  
Date

 (Assignee)  
(Signatory Signature)

Jihwa LEE, Co-representative  
(Assignee Signatory Name, Title)

Docket No. 100257.401 | 8711664\_1